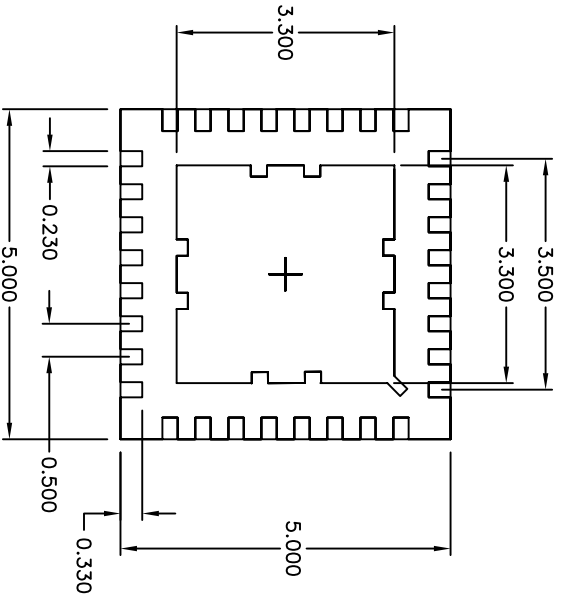
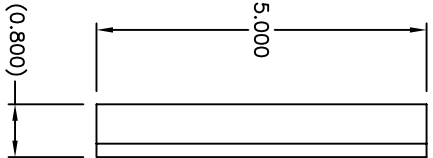
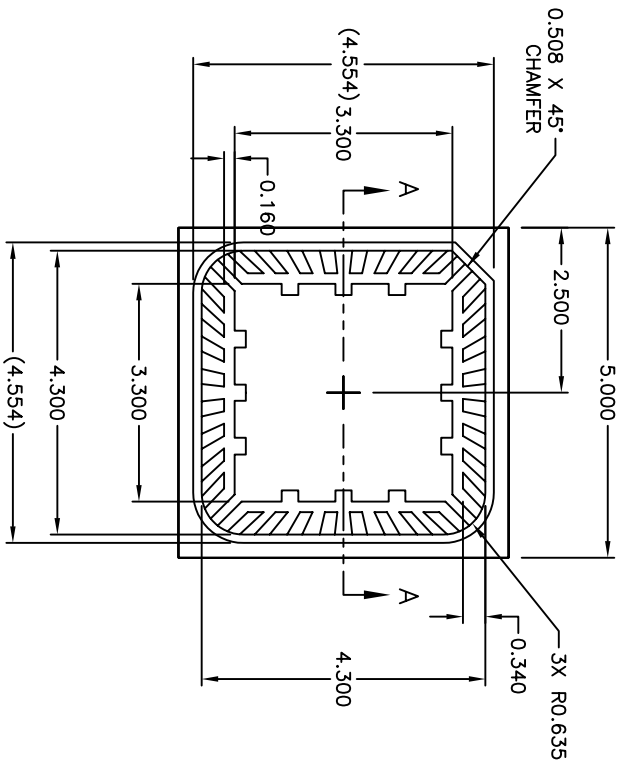


2

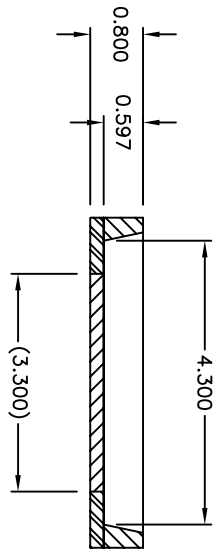
1

SEMPAC REVISIONS			APPROVED
ECON NO.	DATE	DESCRIPTION	D.MORRIS
10760	10/12/06	PRODUCTION RELEASE	



TOP VIEW

BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. LEAD THICKNESS: 0.2030 ±.0076.
 5. DIE PAD: 3.300mm X 3.300mm.
 6. DIE PAD: 3.300mm X 3.300mm.
 7. JEDEC OUTLINE: MO-220 (VHHD-4).



THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: X.XXX ± 0.015 X.XXXX ± .1°

DO NOT SCALE DRAWING

DRAWN BY	C. CRUZ	DATE	10/12/06
APP BY	P. FLASKERUD	DATE	10/12/06
CUSTOMER	---		

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SIZE	PART NO.	REV
A	MLP5X5-32-OP-01	2
SCALE NONE	FILE MLP5X5-32-OP-01-R2.DWG	SHEET 1 OF 1

2

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